

PATENT ASSIGNMENT

Electronic Version v1.1  
 Stylesheet Version v1.1

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
Delphi Technologies, Inc.	06/24/2011
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	Google Inc.
<b>Street Address:</b>	1600 Amphitheatre Parkway
<b>City:</b>	Mountain View
<b>State/Country:</b>	CALIFORNIA
<b>Postal Code:</b>	94043
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	10708936
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	(651)735-1102
<b>Phone:</b>	651-735-1100
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<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via US Mail.</i>	
<b>Correspondent Name:</b>	Shumaker & Sieffert, P.A.
<b>Address Line 1:</b>	1625 Radio Drive
<b>Address Line 2:</b>	Suite 300
<b>Address Line 4:</b>	Woodbury, MINNESOTA 55125
<b>ATTORNEY DOCKET NUMBER:</b>	1133-316US01
<b>NAME OF SUBMITTER:</b>	Rebecca Bartels
<b>Total Attachments: 4</b> source=Delphi-Google Assignment#page1.tif source=Delphi-Google Assignment#page2.tif source=Delphi-Google Assignment#page3.tif source=Delphi-Google Assignment#page4.tif	

CH \$40.00 10708936

## ASSIGNMENT OF PATENT RIGHTS

This Assignment of Patent RIGHTS (the "Assignment") is executed, acknowledged and delivered by Delphi Technologies, Inc., a Delaware company, with its principal place of business at Delphi Drive, Troy, Michigan 48098 ("Assignor"), in accordance with, and pursuant to the terms and conditions of the Patent Purchase Agreement having an Effective Date of May 27, 2011 (the "Agreement") between Assignor, as Seller and Google Inc., a Delaware corporation ("Assignee"). Capitalized terms used herein and not expressly defined shall have the meaning ascribed to such terms in the Agreement.

"Listed Patents" means the provisional patent applications, patent applications, and patents listed on **Exhibit A**.

"Patents" means, all (a) Listed Patents; (b) patents or patent applications (whether expressly enumerated or not in the Listed Patents) (i) to which any of the Listed Patents claims priority, (ii) for which any of the Listed Patents forms a basis for priority, and/or (iii) which are subject to a terminal disclaimer with any of the Listed Patents; (c) reissues, reexaminations, extensions, continuations, continuations in part, continuing prosecution applications, requests for continuing examinations, divisions, and registrations of any item in any of the foregoing categories (a) and (b); and (d) foreign corresponding patents, patent applications and counterparts relating to any item in any of the foregoing categories (a) through (c), including, without limitation, certificates of invention and utility models.

### NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN:

For good and valuable consideration, the receipt of which is hereby acknowledged, Assignor agrees to and does hereby irrevocably sell, assign, transfer and convey unto said Assignee, and Assignee hereby accepts, all of Assignor's right, title, and interest (i) in and to the Patents, the same to be held and enjoyed by said Assignee for its own use, and for the use of its successors, assigns, or other legal representatives to the end of the term or terms for which said Patents may be granted as fully and entirely as the same would have been held and enjoyed by Assignor if this Assignment had not been made; (ii) in and to causes of action and enforcement rights for the Patents including all rights to pursue damages, injunctive relief and other remedies for past and future infringement of the Patents; and (iii) to apply in any and all countries for the world for patents, certificates of invention or other governmental grants for the Patents. Assignor also hereby authorizes the respective patent office or governmental agency in each jurisdiction to issue any and all patents or certificates of invention which may be granted upon any of the Patents in the name of Assignee, as the assignee to the entire interest therein.

Notwithstanding anything to the contrary herein, Assignor is executing and delivering this Assignment in accordance with and subject to all of the terms and provisions of the Agreement. In the event of any conflict between the terms of this Assignment and those of the Agreement, the terms of the Agreement shall be controlling.

This Assignment shall be binding upon and shall inure to the benefit of the parties and their respective successors and assigns.

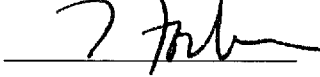
This Assignment shall be governed by, and construed in accordance with, the laws of the United States in respect to patent issues and in all other respects by the laws of the State of California, without giving effect to the conflict of laws rules thereof.

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IN WITNESS WHEREOF, Assignor has caused this Assignment to be executed as of this 24 day of JUNE 2011.

**ASSIGNOR:**

Delphi Technologies, Inc.

By: 

Name: Timothy Forbes

Title: Vice President

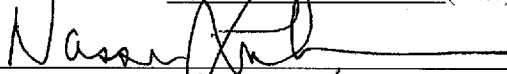
**ATTESTATION**

The undersigned witnessed the signature of TIMOTHY FORBES to the above Assignment of Patent Rights on behalf of Assignor and makes the following statements:

1. I am over the age of 18 and competent to testify as to the facts in this Attestation block if called upon to do so.
2. TIMOTHY FORBES is personally known to me (or proved to me on the basis of satisfactory evidence) and appeared before me on 6/24/11 to execute the above Assignment of Patent Rights on behalf of Assignor.
3. TIMOTHY FORBES subscribed to the above Assignment of Patent Rights on behalf of Assignor.

I declare under penalty of perjury under the laws of the United States of America that the foregoing is true and correct.

EXECUTED on 24 JUNE 2011 (date)

  
Print Name: NASSER LUKMANI

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AMENDED EXHIBIT A

Delphi #	Country	US Patent #	Description
H-186442	US	08/416235	SELF-COMPENSATING ACCELEROMETER
H-198050 CIP to H- 186442	US	5698785	SELF-COMPENSATING ACCELEROMETER
H-194679	US	5721162	ALL-SILICON MONOLITHIC MOTION SENSOR WITH INTEGRATED CONDITIONING CIRCUIT
	EP	0772045	ALL-SILICON MONOLITHIC MOTION SENSOR WITH INTEGRATED CONDITIONING CIRCUIT
	DE	0772045	ALL-SILICON MONOLITHIC MOTION SENSOR WITH INTEGRATED CONDITIONING CIRCUIT
	FR	0772045	ALL-SILICON MONOLITHIC MOTION SENSOR WITH INTEGRATED CONDITIONING CIRCUIT
	GB	0772045	ALL-SILICON MONOLITHIC MOTION SENSOR WITH INTEGRATED CONDITIONING CIRCUIT
H-195981	US	5736641	CAPACITANCE DECODED ACCELEROMETER
H-196719	US	5831162	SILICON MICROMACHINED MOTION SENSOR AND METHOD OF MAKING
H-199261	US	5866796	METHOD AND APPARATUS FOR DETECTING FAILURE IN VIBRATING SENSORS
H-193143	US	5652374	METHOD AND APPARATUS FOR DETECTING FAILURE IN VIBRATING SENSOR
H-198884	US	5872313	TEMPERATURE-COMPENSATED SURFACE MICROMACHINED ANGULAR RATE SENSOR
H-203457	US	6128954	SPRING FOR A RESONANCE RING OF AN ANGULAR RATE SENSOR
	EP	1014037	SPRING FOR A RESONANCE RING OF AN ANGULAR RATE SENSOR
	CH	1014037	SPRING FOR A RESONANCE RING OF AN ANGULAR RATE SENSOR
	DE	1014037	SPRING FOR A RESONANCE RING OF AN ANGULAR RATE SENSOR
	FR	1014037	SPRING FOR A RESONANCE RING OF AN ANGULAR RATE SENSOR
	GB	1014037	SPRING FOR A RESONANCE RING OF AN ANGULAR RATE SENSOR
	NL	1014037	SPRING FOR A RESONANCE RING OF AN ANGULAR RATE SENSOR
H-204679	US	6305222	ROAD VIBRATION COMPENSATED ANGULAR RATE SENSOR
	DE	1055908	ROAD VIBRATION COMPENSATED ANGULAR RATE SENSOR
	FR	1055908	ROAD VIBRATION COMPENSATED ANGULAR RATE SENSOR
	GB	1055908	ROAD VIBRATION COMPENSATED ANGULAR RATE SENSOR
DP- 303435	US	6393914	ANGULAR ACCELEROMETER
DP- 307174	US	6666092	ANGULAR ACCELEROMETER HAVING BALANCED INERTIA MASS
	DE	1340984	ANGULAR ACCELEROMETER HAVING BALANCED INERTIA MASS
	FR	1340984	ANGULAR ACCELEROMETER HAVING BALANCED INERTIA MASS
	GB	1340984	ANGULAR ACCELEROMETER HAVING BALANCED INERTIA MASS
DP- 306551	US	6761070	MICROFABRICATED LINEAR ACCELEROMETER
DP- 311928	US	11/081427	LINEAR ACCELEROMETER
DP- 312388	US	7250322	METHOD OF MAKING MICROSENSOR
	EP	1702884	METHOD OF MAKING MICROSENSOR
DP- 313239	US	7293460	MULTIPLE-AXIS LINEAR ACCELEROMETER
H-194593	US	5663508	SILICON FLOW SENSOR
H-197761	US	5879572	METHOD OF PROTECTING SILICON WAFERS DURING WET CHEMICAL ETCHING
H-198509	US	5915281	SILICON FORCE AND DISPLACEMENT SENSOR
H-199569	US	5932809	SENSOR WITH SILICON STRAIN GAGE
H-201368	US	6062461	PROCESS FOR BONDING MICROMACHINED WAFERS USING SOLDER
DP- 300150	US	6428713	MEMS SENSOR STRUCTURE AND MICROFABRICATION PROCESS THEREFOR
		10/141740	MEMS SENSOR STRUCTURE AND MICROFABRICATION PROCESS THEREFOR
DP- 302242	US	6685844	DEEP REACTIVE ION ETCHING PROCESS AND MICROELECTROMECHANICAL DEVICES FORMED THEREBY

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DP-300151	US	6750152	METHOD AND APPARATUS FOR ELECTRICALLY TESTING AND CHARACTERIZING FORMATION OF MICROELECTRIC FEATURES
H-204402	US	6750521	SURFACE MOUNT PACKAGE FOR A MICROMACHINED DEVICE
DP-307129	US	6828172	PROCESS FOR A MONOLITHICALLY-INTEGRATED MICROMACHINED SENSOR AND CIRCUIT
		10/955,128	PROCESS FOR A MONOLITHICALLY-INTEGRATED MICROMACHINES SENSOR AND CIRCUIT
		60/354,589	PROCESS FOR A MONOLITHICALLY-INTEGRATED MICROMACHINES SENSOR AND CIRCUIT
DP-310613	US	7026645	LEAK DETECTION METHOD AND MICRO-MACHINED DEVICE ASSEMBLY
DP-302242	US	7077007	DEEP REACTIVE ION ETCHING PROCESS AND MICROELECTROMECHANICAL DEVICES FORMED THEREBY
		10/715758	DEEP REACTIVE ION ETCHING PROCESS AND MICROELECTROMECHANICAL DEVICES FORMED THEREBY
DP-309106	US	7118991	ENCAPSULATION WAFER PROCESS
DP-313331	US	7179668	TECHNIQUE FOR MANUFACTURING SILICON STRUCTURES
DP-313244	US	7214324	TECHNIQUE FOR MANUFACTURING MICRO-ELECTRO MECHANICAL STRUCTURES
DP-313662	US	7294552	ELECTRICAL CONTACT FOR A MEMS DEVICE AND METHOD OF MAKING
DP-313333	US	7372115	THERMALLY ISOLATED MEMBRANE STRUCTURE
DP-315105	US	7510894	POST LOGIC ISOLATION OF SILICON
DP-313246	US	7524767	METHOD FOR MANUFACTURING A MICRO-ELECTRO-MECHANICAL STRUCTURE
DP-313247	US	7534641	METHOD FOR MANUFACTURING A MICRO-ELECTRO-MECHANICAL DEVICE
DP-309079	US	11/414851	MICROFLUIDIC VALVE STRUCTURE

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